

Bill of Materials

TI DESIGNS

Footprint	Comment	LibRef	Designator	Description	Quantity
TSSOP-38P	MSP430G2955_TSSO	MSP430G2X55_TSSOP	U2		1
SOT-23-5P	TLV70233_SOT23-5	TLV70233_SOT23-5	U1		1
0603-R		Res2	R1, R2, R3, R4, R5, R6, R7, R8, R9, R10, R11, R12, R13, R14, R15, R16, R17, R18, R19, R20, R21, R22, R23, R24, R25, R26, R27, R28, R29, R30, R31, R32, R33, R34, R35, R36, R37, R38, R39, R40, R41, R42, R43, R44, R45, R46, R47, R48, R49, R50, R51, R52, R53, R54, R55, R56, R57	Resistor	57
SOT-23B	QNPN	QNPN	Q1, Q2, Q3, Q4, Q5, Q6, Q7, Q8, Q9, Q10, Q11, Q12, Q13, Q14, Q15, Q16, Q17, Q18, Q19, Q20, Q21, Q22, Q23, Q24	NPN Bipolar Transistor	24
		PAD	KEY1, KEY2, W0, W1, W2, W3		6
USBSTD	Mini_USB	Mini_USB	J3		1
HDR1X2		DIP2	J2		1
HDR2X7	JTAG_2X7	JTAG_2X7	J1		1
0603-C	1UF	CAP-SMD	EC2		1
0603-C	10uF/16V	CAP-EC	EC1		1
LED0805_H		LED3	D1, D2, D3, D4, D5, D6, D7, D8, D9, D10, D11, D12, D13, D14, D15, D16, D17, D18, D19, D20, D21, D22, D23, D24	Typical BLUE SiC LED	24
0603-C	2.2nF	CAP-SMD	C5		1
0603-C	104	CAP-SMD	C1, C2, C3, C4		4
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